PROCESS FOR CLEAVING LAYERS OF A WAFER OF MATERIAL

ABSTRACT

The invention relates to a Process for cleaving two layers of a wafer along an embrittled surface defined between the two layers, the process comprising a thermal anneal for the purpose of cleaving the wafer comprising said layers, characterized in that said wafer is arranged in a substantially horizontal direction during the annealing process.

The invention also relates to the application of this process and an associated device (30).

FIGURE 1

162162

G00002